



40V NPN SMALL SIGNAL TRANSISTOR IN SOT323

Features

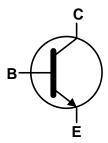
- BV_{CEO} > 40V
- I_C = 600mA Collector Current
- Epitaxial Planar Die Construction
- Ultra-Small Surface Mount Package
- Complementary PNP Type: MMST2907A
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

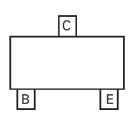
- Case: SOT323
- Case Material: Molded Plastic. "Green" Molding Compound;
 UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ©3
- Weight: 0.006 grams (Approximate)







Device Symbol



Pin-Out Top View

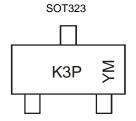
Ordering Information (Note 4)

Product	Status	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
MMST2222A-7-F	NRND	AEC-Q101	K3P	7	8	3,000
MMST2222A-7	Active	AEC-Q101	K3P	7	8	3,000

Notes

- $1.\ No\ purposely\ added\ lead.\ Fully\ EU\ Directive\ 2002/95/EC\ (RoHS)\ \&\ 2011/65/EU\ (RoHS\ 2)\ compliant.$
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. NRND = Not Recommended for New Design. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



K3P = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: A = 2013) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Year	2013	2	2014	2015	2016	2017	2018	2019	9 20	20	2021	2022	2023
Code	Α		В	С	D	Е	F	G	ŀ	-		J	K
Montl	h	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code		1	2	3	4	5	6	7	8	9	0	N	D



Absolute Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	75	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current	Ic	600	mA

Thermal Characteristics (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _d	200	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range	T _i , T _{STG}	-55 to +150	°C

ESD Ratings (Note 6)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	٧	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)			•	•	
Collector-Base Breakdown Voltage	BV _{CBO}	75	_	V	$I_C = 10\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	BV _{CEO}	40	_	V	I _C = 10mA, I _B = 0
Emitter-Base Breakdown Voltage	BV _{EBO}	6.0	_	V	$I_E = 10\mu A, I_C = 0$
Collector Cut-Off Current	I _{CBO}		10	nΑ μΑ	V _{CB} = 60V, IE = 0 V _{CB} = 60V, IE = 0, TA = +150°C
Collector Cut-Off Current	I _{CEX}	_	10	nA	$V_{CE} = 60V$, $V_{EB(OFF)} = 3V$
Base Cutoff Current	I _{BL}	_	20	nA	$V_{CE} = 60V$, $V_{EB(OFF)} = 3V$
ON CHARACTERISTICS (Note 7)					·
DC Current Gain	h _{FE}	35 50 75 100 40 50 35		_	$\begin{split} I_C &= 100 \mu A, \ V_{CE} = 10 V \\ I_C &= 1.0 m A, \ V_{CE} = 10 V \\ I_C &= 10 m A, \ V_{CE} = 10 V \\ I_C &= 150 m A, \ V_{CE} = 10 V \\ I_C &= 500 m A, \ V_{CE} = 10 V \\ I_C &= 10 m A, \ V_{CE} = 10 V, \ T_A = -55 ^{\circ} C \\ I_C &= 150 m A, \ V_{CE} = 1.0 V \end{split}$
Collector-Emitter Saturation Voltage	V _{CE(sat)}		0.3 1.0	V	$I_C = 150$ mA, $I_B = 15$ mA $I_C = 500$ mA, $I_B = 50$ mA
Base-Emitter Saturation Voltage	V _{BE(sat)}	0.6	1.2 2.0	V	$I_C = 150 \text{mA}, I_B = 15 \text{mA}$ $I_C = 500 \text{mA}, I_B = 50 \text{mA}$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	Cobo	_	8	pF	$V_{CB} = 10V, f = 1.0MHz, I_{E} = 0$
Input Capacitance	C _{ibo}	_	25	pF	$V_{EB} = 0.5V$, $f = 1.0MHz$, $I_{C} = 0$
Current Gain-Bandwidth Product	f⊤	300	_	MHz	$V_{CE} = 20V$, $I_C = 20mA$, $f = 1.0MHz$
Noise Figure	NF		4.0	dB	$V_{CE} = 10V, I_{C} = 100 \mu A,$ $R_{S} = 1k\Omega, f = 1.0kHz$
SWITCHING CHARACTERISTICS					
Delay Time	t _d	_	10	ns	$V_{CC} = 30V, I_C = 150mA,$
Rise Time	t _r	_	25	ns	$V_{BE(OFF)} = -0.5V, I_{B1} = 15mA$
Storage Time	ts		225	ns	$V_{CC} = 30V, I_C = 150mA,$
Fall Time	t _f		60	ns	$I_{B1} = I_{B2} = 15mA$

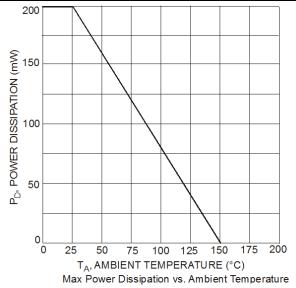
Notes: 5. For a device mounted with the collector lead on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.

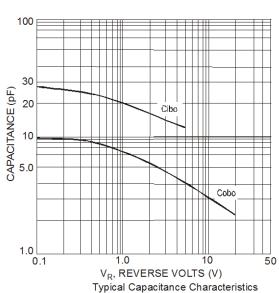
^{6.} Refer to JEDEC specification JESD22-A114 and JESD22-A115.

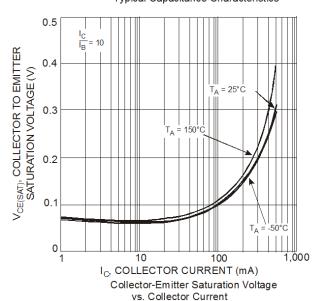
^{7.} Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

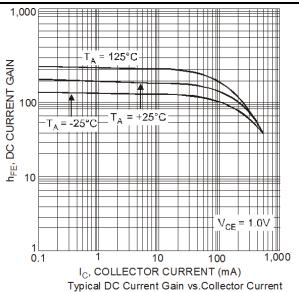


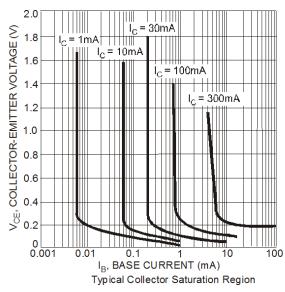
Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

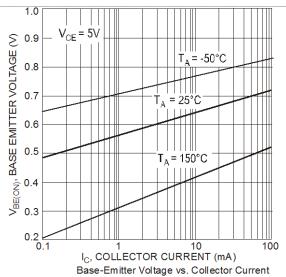




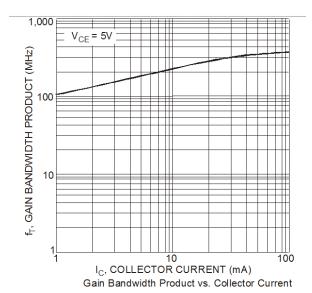








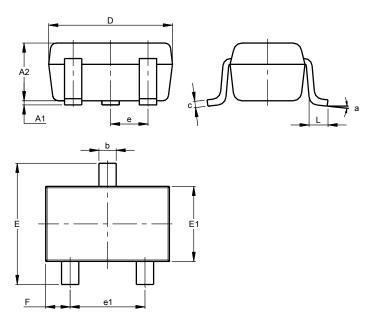






Package Outline Dimensions

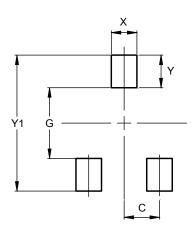
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT323						
Dim	Min	Max	Тур			
A1	0.00	0.10	0.05			
A2	0.90	1.00	0.95			
b	0.25	0.40	0.30			
С	0.10	0.18	0.11			
D	1.80	2.20	2.15			
Е	2.00	2.20	2.10			
E1	1.15	1.35	1.30			
е	0).650 B	SC			
e1	1.20	1.40	1.30			
F	0.375	0.475	0.425			
L	0.25	0.40	0.30			
а	8°					
All	Dimen	sions i	in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value
Difficilisions	(in mm)
С	0.650
G	1.300
Х	0.470
Y	0.600
Y1	2.500



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